Datasheet for DS90UH926Q-Q1, DS90UB926Q-Q1, DS90UH302Q-Q1, and DS90UB302Q-Q1 Despublished Dept: Quality Services Dept: Quality Services Dept: Quality Services Dept: Quality Services Description Design Wafer Bump Site Wafer Bump Material Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Wafer Fab Site Wafer Fab Materials Wafer Fab Materials Wafer Fab Materials Wafer Fab Materials Wafer Fab Process	PCN Number: 20170724000 PCN Date: August 4, 2017					.017					
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Changed Typical Display System Diagram (removed MCLK)	47										
	•	Changed Power-Up Requirements and PDB pin description and added Power-Up Sequence graphic									
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Deleted reference to MCLK in this section	12
Deleted reference to MCLK	27
Changed MCLK section	
Changed MCLK columns of Audio Interface Frequencies table	2 7
Changed the values in columns 2 through 5 in Configuration Select (MODE_SEL) table	
Changed the values in columns 2 to 5 in Serial Control Bus Addresses for IDx table	
Changed register reference to MCLK	
Changed Typical Display System Diagram (removed reference to MCLK)	
Changed wording of Power Up Requirements and PDB Pin subsection and added Power-Up Sequence graphic	
TEXAS INSTRUMENTS DS90UH3 SNLS425B – NOVEMBER 2016– REVISED	
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INSTRUMENTS SNLS425B – NOVEMBER 2016 – REVISED anges from Revision A (April 2013) to Revision B	Page
INSTRUMENTS SNLS425B – NOVEMBER 2016 – REVISED anges from Revision A (April 2013) to Revision B	Page
INSTRUMENTS SNLS425B – NOVEMBER 2016 – REVISED anges from Revision A (April 2013) to Revision B Changed HBM ESD classification level from: ±8 kv to: 3B	Page
INSTRUMENTS anges from Revision A (April 2013) to Revision B Changed HBM ESD classification level from: ±8 kv to: 3B	Page
anges from Revision A (April 2013) to Revision B Changed HBM ESD classification level from: ±8 kv to: 3B Deleted Product Preview marking Added Device Information and Pin Configuration and Functions sections, ESD Ratings and Thermal Information tables, Feature Description, Device Functional Modes, Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information sections. Deleted sentence "EMI is minimized by the use of low voltage differential signaling, data scrambling and randomization and spread-spectrum clocking compatibility."	Page
INSTRUMENTS anges from Revision A (April 2013) to Revision B Changed HBM ESD classification level from: ±8 kv to: 3B	Page
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The datasheet number will be changing.

Device Family	Change From:	Change To:
DS90UH926Q-Q1	SNLS337K	SNLS337M
DS90UB926Q-Q1	SNLS422B	SNLS422D
DS90UH302Q-Q1	SNLS425A	SNLS425B
DS90UB302Q-Q1	SNLS410B	SNLS410C

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/DS90UH926Q-Q1

http://www.ti.com/product/DS90UB926Q-Q1

DS90UH302Q-Q1 and DS90UB302Q-Q1; the document is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DS90UH926QSQ/NOPB	DS90UH926QSQE/NOPB	DS90UH926QSQX/NOPB	DS90UB926QSQ/NOPB
DS90UB926QSQE/NOPB	DS90UB926QSQX/NOPB	DS90UB302QSQ/NOPB	DS90UB302QSQE/NOPB
DS90UB302QSQX/NOPB	DS90UH302QSQ/NOPB	DS90UH302QSQE/NOPB	DS90UH302QSQX/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com